TITLE: CHIP SCALE PACKAGE WITH HEAT SPREADER AND METHOD OF MANUFACTURE
Inventor: David J. Corisis
Serial No.: 09/342,789
Docket No.: 2269-3384.1US
REPLACEMENT SHEET

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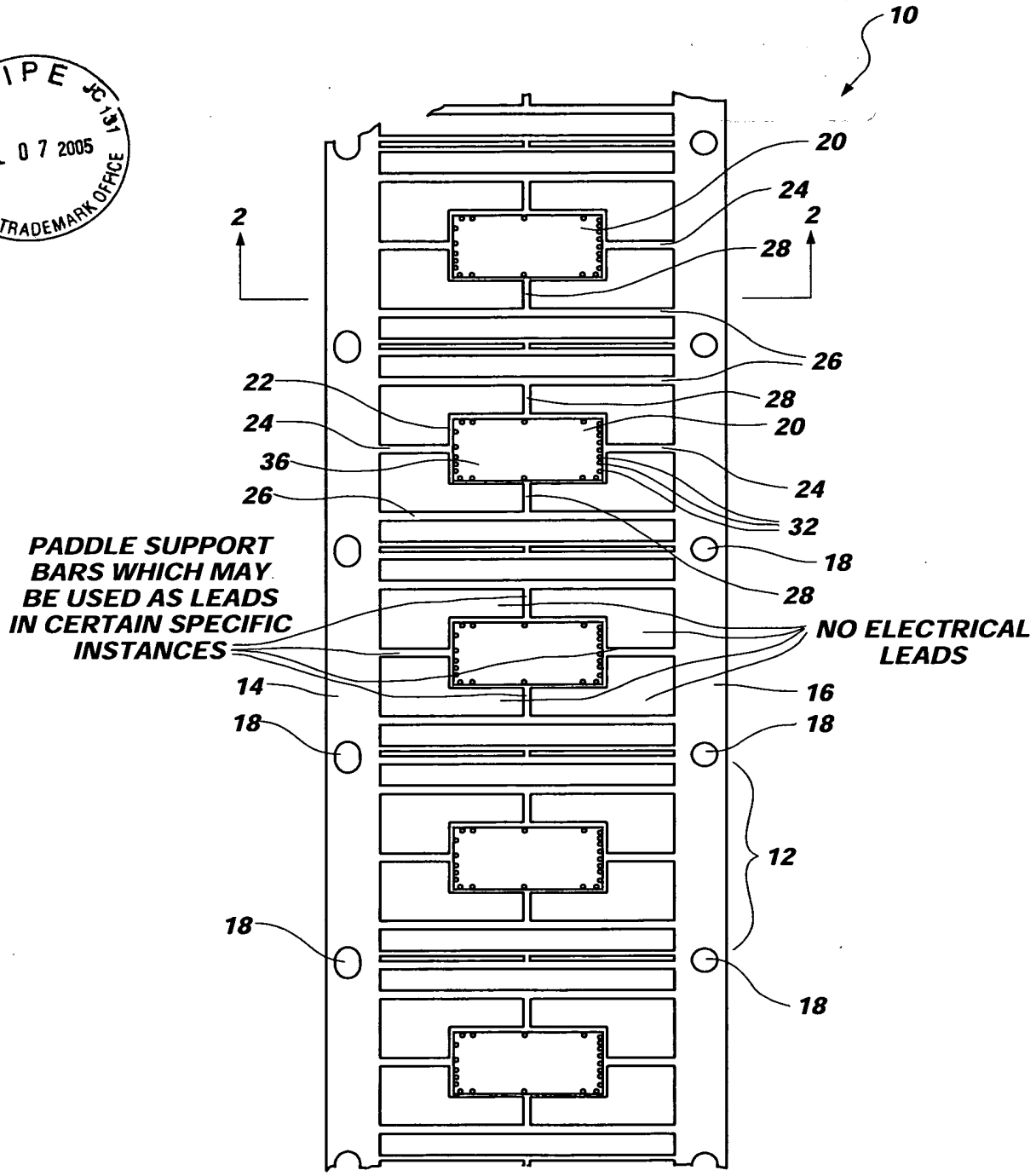



Fig. 1